

STI No. 1157

Docket No. AUS920030594US1

In place of Form PTO-1595

RECORDATION FORM COVER SHEET
PATENTS

To the Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

(1) Hiruki Kihara

Execution Date:

April 8, 2004

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):

Sony Computer Entertainment Inc.
1-1, Akasaka 7-chome,
Minato-ku
Tokyo, 107-0052 Japan

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is
(1) _____A. Patent Application No.(s) 10/850,400 B. File Date May 20, 20045. Name and address of party to whom
correspondence concerning document
should be mailed:Robert M Carwell
IBM Corporation
Intellectual Property Law
11400 Burnet Road
Austin, TX 78758
(512) 823-10176. Total number of applications and patents
involved: 17. Total fee (37 CFR 3.41) \$ 40.00☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number:

09/0447

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy
of the original documentKathryn L. Seaman
Name of Person SigningKathryn L. Seaman
SignatureJuly 30, 2004
DateTotal number of pages including cover sheet. 2

STI #: 1157
IBM Docket No.:AUS920031086US1

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: HIGH FREQUENCY DIVIDER STATE CORRECTION CIRCUIT WITH DATA PATH CORRECTION

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 2-6-21, Minami Aoyama, Minato-ku, Tokyo, 107-0062 Japan, (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said applications, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patent, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest therein;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said applications for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

Hiroki Kihara
Name of First or Sole Inventor

7600 Tovar Drive, Austin, Texas 78729
Residence of First or Sole Inventor

Hiroki Kihara
Signature of First or Sole Inventor

4/8/2004
Date of this Assignment